NL3S22AH, NL3S22UH

USB 2.0 + Audio Switch

The NL3S22AH/NL3S22UH is a double−pole/double−throw (DPDT) analog switch for routing high speed differential data and audio. The differential channels are compliant with High Speed USB 2.0, Full Speed USB 1.1, Low Speed USB 1.0 and any generic UART protocol. The multi−purpose audio path is capable of passing signals with negative voltages as low as 3 V below ground and features shunt resistors to reduce Pop and Click noise in the audio system.

For the NL3S22AH, the audio path (AUDP/AUDN) will be selected with SEL=0 with the device enabled (EN = 1). For the NL3S22UH, the high speed data path (HDP/HDN) will be selected with SEL=0 with the device enabled (EN = 1).

Features

- V_{CC} Range: 2.7 V to 3.7 V
- Control Pins Compatible with 1.8 V Interfaces
- I_{CC}: 60 μA (Typ)
- ESD Performance: 2 kV HBM
- Available in 1.4 mm x 1.8 mm UQFN10
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

High Speed Data Path

- Input Signal Range: 0 V to 4.5 V
- $R_{DS(on)}$: 5.4 Ω (Typ)
- C_{ON}: 8.7 pF (Typ)
- Data Rate: USB 2.0–Compliant – up to 480 Mbps
- Bandwidth: >811 MHz

Audio Path

- Input Signal Range: −3.0 V to 3.0 V
- R_{DSON}: 0.56 Ω (Typ)
- $R_{ON(FLAT)}$: 0.004 Ω (Typ)
- THD+N:
  - − 113 dB (R_L = 32 Ω / V_{IS} = 1.0 V_{RMS})
  - − 109 dB (R_L = 16 Ω / V_{IS} = 0.4 V_{RMS})

Applications

- Smartphones
- Tablets
- USB 2.0 Hosts/Peripherals
- Audio / High−Speeds Data Switching
- USB Type−C Switching

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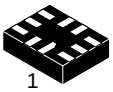
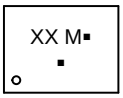
MARKING DIAGRAM



UQFN10
CASE 488AT



XX = AY for NL3S22AHMUTAG
= DW for NL3S22UHMUTAG
M = Date Code
▪ = Pb−Free Device
(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
NL3S22AHMUTAG	UQFN10 (Pb−Free)	3000 / Tape & Reel
NL3S22UHMUTAG	UQFN10 (Pb−Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

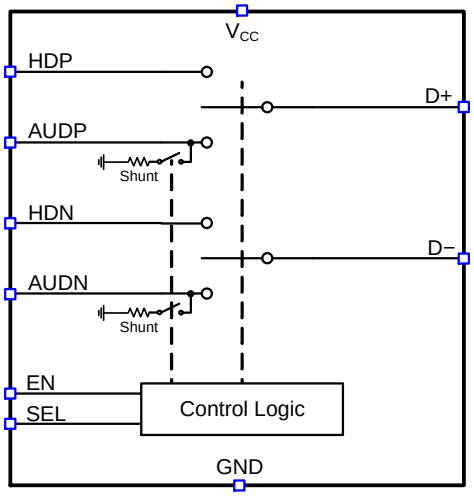


Figure 1. Block Diagram

FUNCTION TABLE

EN	SEL		Shunt Status	D+/D− Function
	NL3S22AH	NL3S22UH		
0	X	X	ON	No Connect (Power Down)
1	0	1	OFF	AUDP/AUDN
1	1	0	ON	HDP/HDN

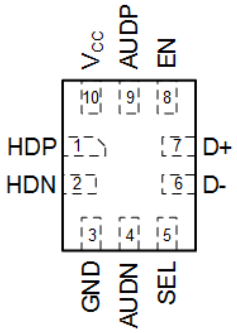


Figure 2. UQFN10 – Top Through View

PIN DESCRIPTION

Pin Name	Pin	Description
HDP	1	High Speed Differential Data (+)
HDN	2	High Speed Differential Data (−)
GND	3	Ground
AUDN	4	Audio Signal (−)
SEL	5	Function Select
D−	6	Audio/Data Common I/O (−)
D+	7	Audio/Data Common I/O (+)
EN	8	Chip Enable
AUDP	9	Audio Signal (+)
V_{CC}	10	Power Supply

MAXIMUM RATINGS

Rating	Symbol		Value	Unit
V_{CC}	Positive DC Supply Voltage		−0.5 to +4.2	V
V_{IS}	Analog Input/Output Voltage	HDP, HDN	−0.5 to +5.5	V
		AUDP, AUDN	−3.5 to +4.2	
		D+, D−	−3.5 to +5.5	
V_{IN}	Digital Control Pin Voltage on EN, SEL		−0.5 to V_{CC} + 0.5	V
T_s	Storage Temperature		−55 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 seconds		260	°C
T_J	Junction Temperature Under Bias		150	°C
MSL	Moisture Sensitivity (Note 1)		Level 1	
I_{LU}	Latchup Current (Note 2)		±100	mA
ESD	ESD Protection (Note 3)	Human Body Model Charged Device Model	2000 2000	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Moisture Sensitivity Level (MSL): 1 per IPC/JEDEC standard: J−STD−020A.
2. Latch up Current Maximum Rating: ±100 mA per JEDEC standard: JESD78.
3. This device series contains ESD protection and passes the following tests:
   Human Body Model (HBM) ±2.0 kV per JEDEC standard: JESD22−A114 for all pins.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V_{CC}	Positive DC Supply Voltage		2.7	3.7	V
V_{IS}	Switch Input / Output Voltage (Note 4)	HDP, HDN	0	4.5	V
		AUDP, AUDN	−3.0	3.0	
		D+, D−	−3.0	4.5	
V_{IN}	Digital Control Input Voltage		GND	V_{CC}	V
T_A	Operating Temperature Range		−40	+85	°C

4. If the audio channel is not in use, it is recommended that no signals are applied on the audio inputs AUDN and AUDP.

DC ELECTRICAL CHARACTERISTICS (Typical values are at V_{CC} = +3.6 V and T_A = +25°C, unless otherwise specified)

Symbol	Parameter	Test Conditions	V_{CC} (V)	−40 °C to 85 °C			Unit
				Min	Typ	Max	
POWER SUPPLY							
I_{CC}	Supply Current	EN = 1, I_{IS} = 0 mA	3.6	−	60	100	μA
		EN = 0 (Power Down)		−	−	1.0	
Control Logic (EN, SEL)							
V_{IH}	Input High Voltage		3.6	1.4	−	−	V
			2.7	1.3	−	−	
V_{IL}	Input Low Voltage		3.6	−	−	0.4	V
			2.7	−	−	0.4	
V_{IHYS}	Input Hysteresis		2.7 – 3.6	−	250	−	mV
I_{IN}	Leakage Current		2.7 – 3.6	−	−	±100	nA
AUDIO SWITCH (AUDP/AUDN ↔ D+/D−)							
R_{ON}	ON−Resistance	V_{IS} = −3.0 V to 3.0 V, I_{IS} = 50 mA	3.0	−	0.56	0.73	Ω
ΔR_{ON}	ON−Resistance Matching Between Channels	V_{IS} = −3.0 V to 3.0 V, I_{IS} = 50 mA	3.0	−	0.07	−	Ω
$R_{FLAT(ON)}$	ON Resistance Flatness	V_{IS} = −3.0 V to 3.0 V, I_{IS} = 50 mA	3.0	−	0.004	−	Ω
R_{SH}	Shunt Resistance		3.6	−	110	200	Ω
$I_{SW(OFF)}$	OFF−State Leakage	EN = 0, V_{IS} = 3.0 V at D+/D−	3.6	−	−	±200	nA
$I_{SW(ON)}$	ON−State Leakage	V_{IS} = 0 V to 3.0 at D+/D−, AUDP = AUDP = open	3.6	−	±2.2	±3.0	μA
DATA SWITCH (HDP/HDN ↔ D+/D−)							
R_{ON}	ON−Resistance	V_{IS} = 0 V to 1.7 V, I_{IS} = 15 mA	3.0	−	5.4	6.63	Ω
ΔR_{ON}	ON−Resistance Matching Between Channels	V_{IS} = 0 V to 1.7 V, I_{IS} = 15 mA	3.0	−	0.2	−	Ω
$R_{FLAT(ON)}$	ON Resistance Flatness	V_{IS} = 0 V to 1.7 V, I_{IS} = 15 mA	3.0	−	0.002	−	Ω
$I_{SW(OFF)}$	OFF−State Leakage	EN = 0, V_{IS} = 0 V to 3.6 V	3.6	−	−	±200	nA
$I_{SW(ON)}$	ON−State Leakage	V_{IS} = 0 V to 3.6 V	3.6	−	−	±200	nA

AC ELECTRICAL CHARACTERISTICS (Typical values are at V_{CC} = +3.6 V and T_A = +25°C)

Symbol	Parameter	Test Conditions	V_{CC} (V)	−40 °C to 85 °C			Unit
				Min	Typ	Max	
AUDIO SWITCH (AUDP/AUDN ↔ D+/D−)							
THD	Audio THD	f = 20 Hz to 20 kHz, V_{IS} = 1.0 V_{RMS}, DC Bias = 0 V, R_L = 32 Ω V_{IS} = 0.4 V_{RMS}, DC Bias = 0 V, R_L = 16 Ω	2.7 – 3.6	−	 −113 −109	−	dB
PSRR	Power Supply Ripple Rejection	From V_{CC} unto AUDP/AUDN, f = 217 Hz, R_L = 16 Ω	2.7 – 3.6	−	106	−	dB
DATA SWITCH (HDP/HDN ↔ D+/D−)							
C_{ON}	Equivalent ON−Capacitance	Switch ON, f = 1 MHz	3.6	−	8.7	10	pF
C_{OFF}	Equivalent OFF−Capacitance	Switch OFF, f = 1 MHz	3.6	−	1.8	−	pF
D_{IL}	Differential Insertion Loss	f = 10 MHz	2.7 – 3.6	−	−0.5	−	dB
		f = 800 MHz	2.7 – 3.6	−	−2.8	−	
D_{ISO}	Differential Off−Isolation	f = 10 MHz	2.7 – 3.6	−	−54	−	dB
		f = 800 MHz	2.7 – 3.6	−	−25	−	
D_{CTK}	Differential Crosstalk	f = 10 MHz	2.7 – 3.6	−	−62	−	dB
		f = 800 MHz	2.7 – 3.6	−	−28	−	
PSRR	Power Supply Ripple Rejection	From V_{CC} unto D+/D−, f = 217 Hz, R_L = 50 Ω	2.7 – 3.6	−	111	−	dB
DYNAMIC TIMING							
t_{PD}	Propagation Delay (Notes 5 and 6)	V_{NOn} or V_{NCn} = 0V, R_L = 50 Ω	2.7 – 3.6	−	0.25	−	ns
t_{EN}	Enable Time, EN to HDx EN to AUDx	V_{IS} = 1 V, R_L = 50 Ω, C_L = 7 pF (fixture only)	2.7 – 3.6	 − −	 2.1 5.1	 − −	µs
t_{DIS}	Disable Time, EN to HDx EN to AUDx	V_{IS} = 1 V, R_L = 50 Ω, C_L = 7 pF (fixture only)	2.7 – 3.6	 − −	 157 53	 − −	ns
t_{ON}	Turn−On Time, SEL to HDx SEL to AUDx	V_{IS} = 1 V, R_L = 50 Ω, C_L = 7 pF (fixture only)	2.7 – 3.6	 − −	 0.3 3.4	 − −	µs
t_{OFF}	Turn−Off Time, SEL to HDx SEL to AUDx	V_{IS} = 1 V, R_L = 50 Ω, C_L = 7 pF (fixture only)	2.7 – 3.6	 − −	 157 44	 − −	ns
t_{INIT}	Initialization Time (Notes 5 and 7), V_{CC} to D+/D−	V_{IS} = 1 V, R_L = 50 Ω, C_L = 7 pF (fixture only)	2.7 – 3.6	150	−	−	µs
$t_{sk(b-b)}$	Bit to bit skew	Within the same differential channel	2.7 – 3.6	−	5	−	ps
$t_{sk(ch-ch)}$	Channel to channel skew	Maximum skew between all channels	2.7 – 3.6	−	5	−	ps

5. Guaranteed by design.
6. No other delays than the RC network formed by the load resistance and the load capacitance of the switch are added on the bus. For a 10 pF load, this delay is 5 ns which is much smaller than rise and fall time of typical driving systems. Propagation delays on the bus are determined by the driving circuit on the driving side and its interactions with the load of the driven side.
7. Wait time required after V_{CC} power−up to operating level before data access is valid.

PARAMETER MEASUREMENT INFORMATION

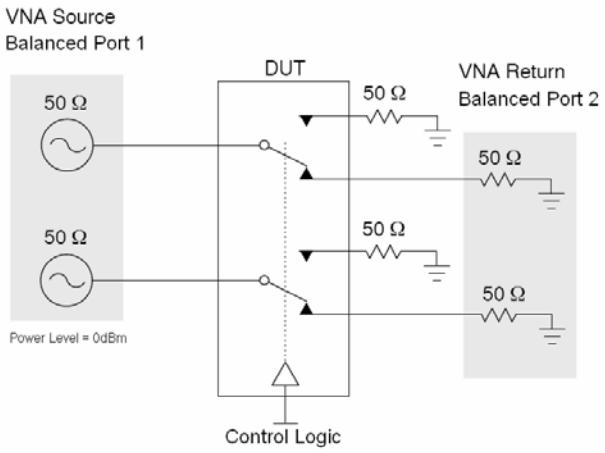


Figure 3. Differential Insertion Loss (S_{DD21})

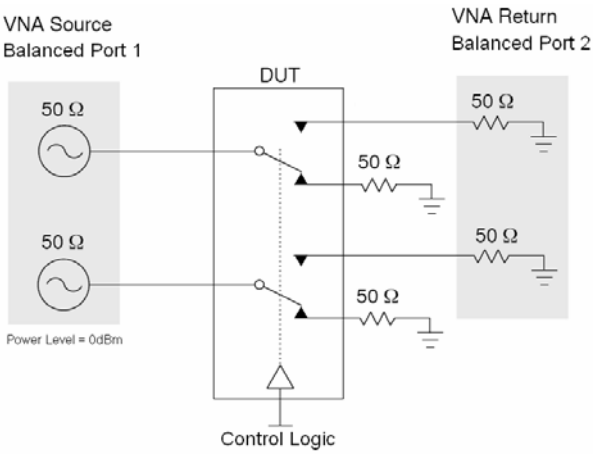


Figure 4. Differential Off Isolation (S_{DD21})

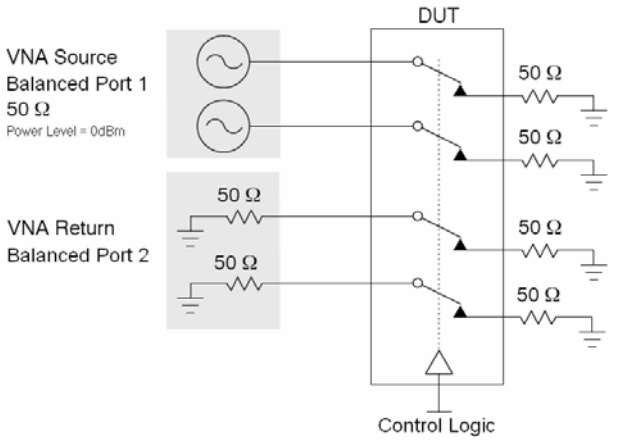
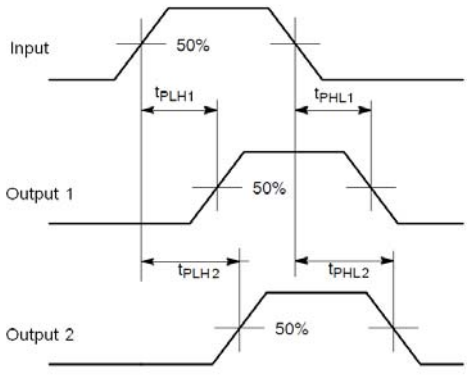
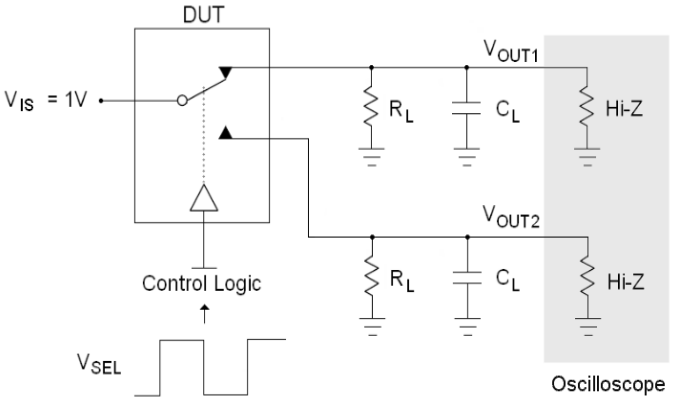


Figure 5. Differential Crosstalk (S_{DD21})



$t_{skew} = |t_{PLH1}-t_{PLH2}|$ or $|t_{PHL1}-t_{PHL2}|$

Figure 6. Bit−to−Bit and Channel−to−Channel Skew



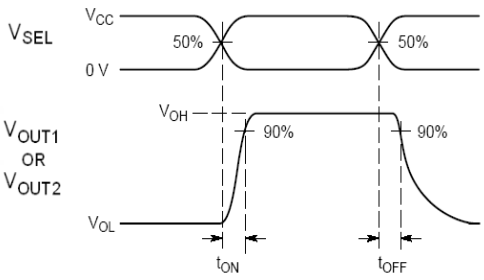


Figure 7. t_{ON} and t_{OFF}

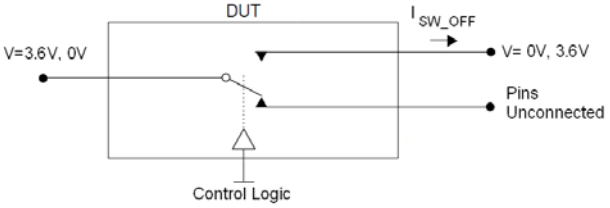


Figure 8. Off State Leakage

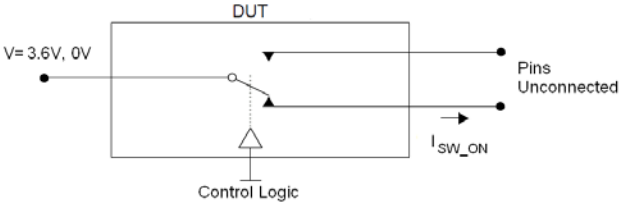


Figure 9. On State Leakage

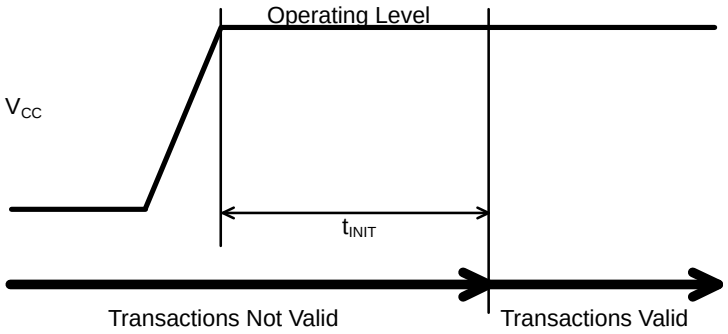


Figure 10. t_{INIT}, Initialization Time

TYPICAL OPERATING CHARACTERISTICS

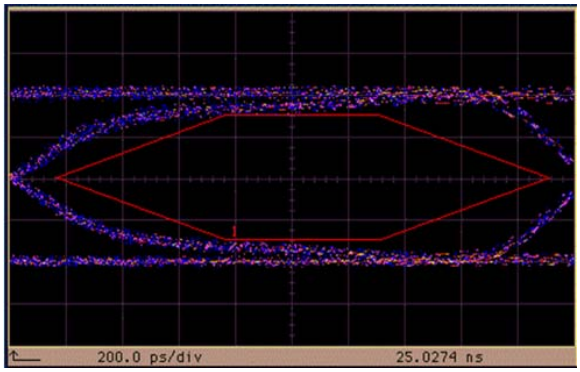


Figure 11. USB 2.0 High Speed Eye Diagram

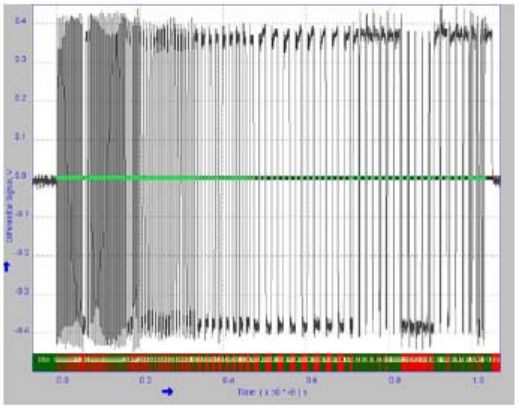


Figure 12. USB 2.0 High Speed Pattern

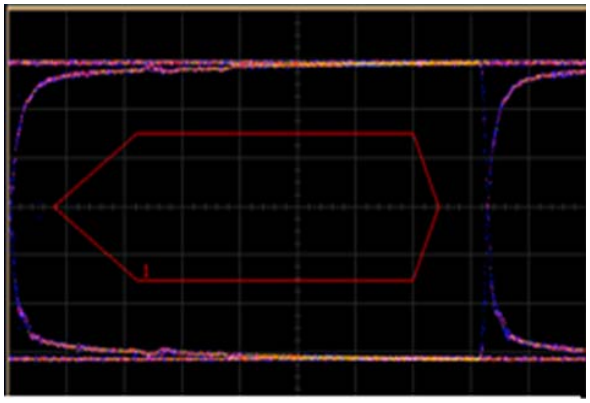


Figure 13. USB 1.1 Full Speed Eye Diagram

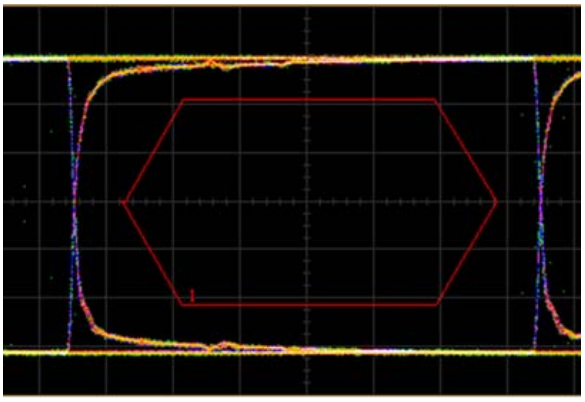


Figure 14. USB 1.0 Low Speed Eye Diagram

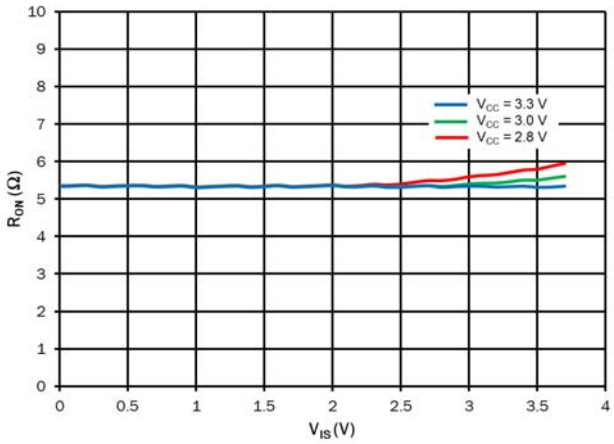


Figure 15. Data Path On Resistance

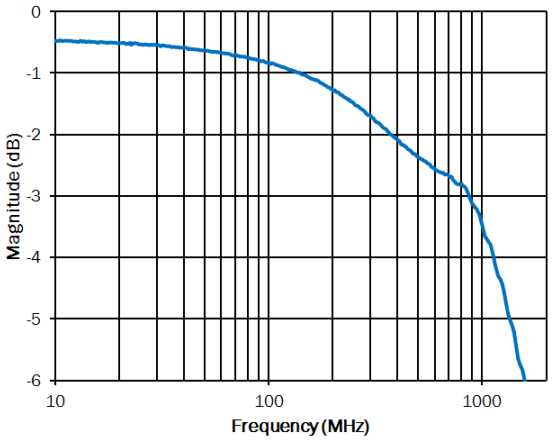


Figure 16. Data Switch Differential Insertion Loss

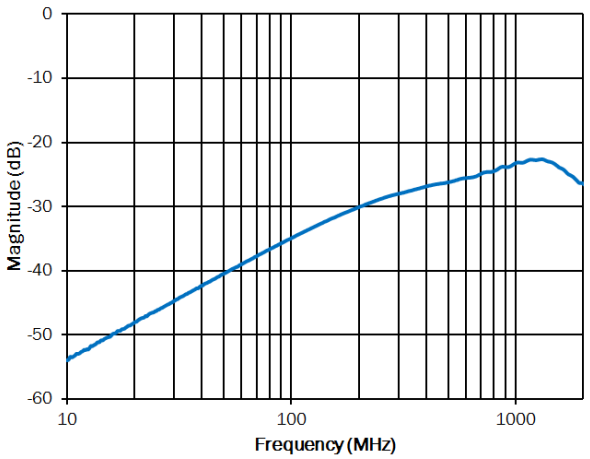


Figure 17. Data Switch Differential Off−Isolation

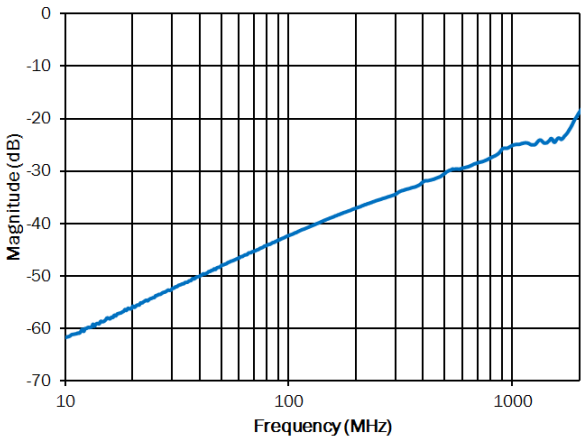


Figure 18. Data Switch Differential Crosstalk

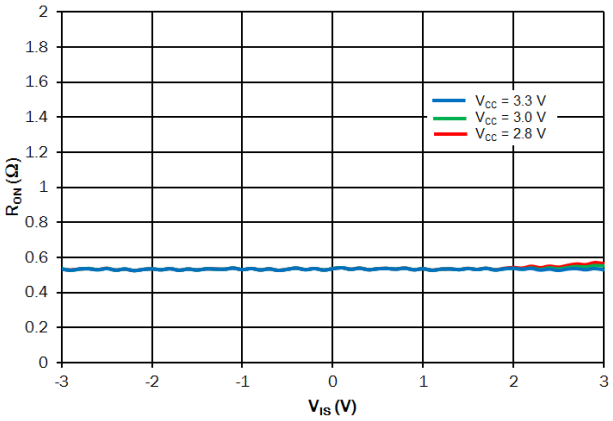


Figure 19. Audio Path On Resistance

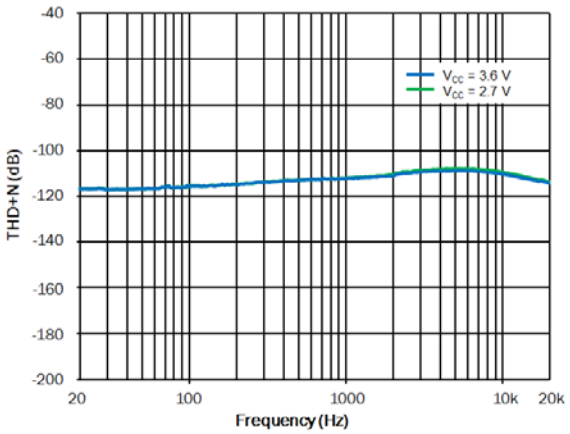


Figure 20. Audio THD+N (R_L = 32 Ω, V_{IS} = 1.0 V_{RMS})

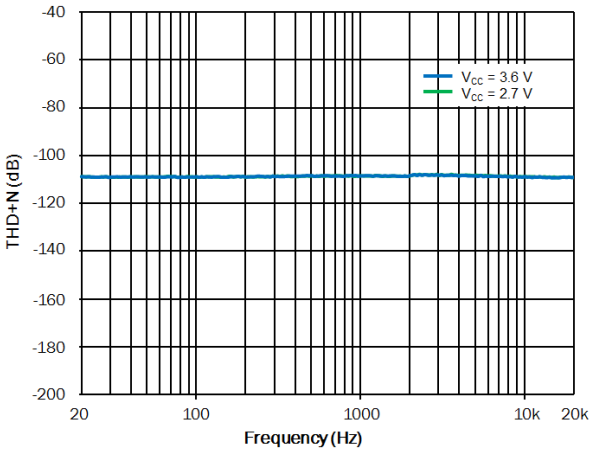


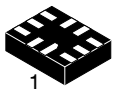
Figure 21. Audio THD+N (R_L = 16 Ω, V_{IS} = 0.4 V_{RMS})

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

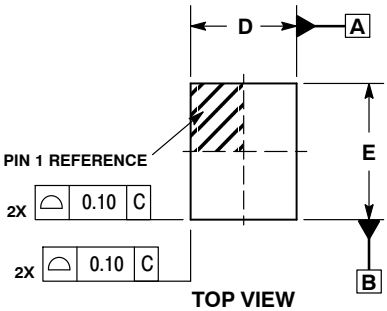
ON Semiconductor®

UQFN10 1.4x1.8, 0.4P
CASE 488AT−01
ISSUE A

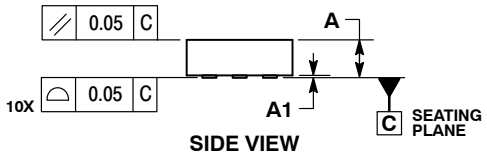
DATE 01 AUG 2007



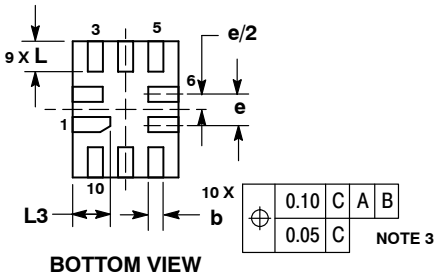
SCALE 5:1



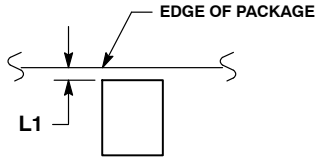
TOP VIEW



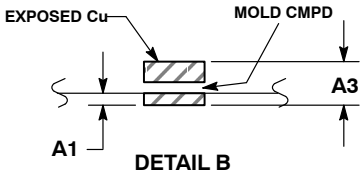
SIDE VIEW



BOTTOM VIEW



DETAIL A
Bottom View
(Optional)

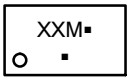


DETAIL B
Side View
(Optional)

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.45	0.60
A1	0.00	0.05
A3	0.127 REF	
b	0.15	0.25
D	1.40 BSC	
E	1.80 BSC	
e	0.40 BSC	
L	0.30	0.50
L1	0.00	0.15
L3	0.40	0.60

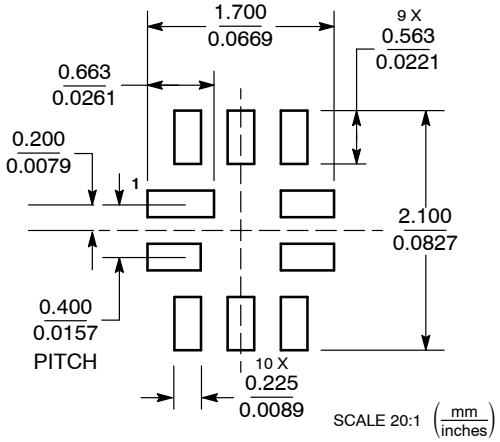
GENERIC MARKING DIAGRAM*



XX = Specific Device Code
M = Date Code
▪ = Pb−Free Package
(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

MOUNTING FOOTPRINT



SCALE 20:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

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DESCRIPTION:	**10 PIN UQFN, 1.4 X 1.8, 0.4P**	**PAGE 1 OF 1**

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